



Embedded Fanless System



TINO 2PCI

TINO

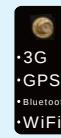
MiTex

Back Panel Motherboard I/O



Blue-marked area is for extra functions

Back Panel Expansion I/O Possibilities & more



Including, but not limited to these functions

Motherboard		CI770A-6C	CI847AW	CI847AW
System Dimension(WxDxH)		268W x 182D x 110H mm	245W x 177D x 68H mm	266W x 204D x 86.5H mm
Weight(Incl.M/B)		6 kg	2.9 kg	2.8 kg
CPU		Intel Mobile Ivy Bridge Processor	Intel Ivy Bridge Celeron 1047 UE 1.4 Ghz; i3, i7	Intel Ivy Bridge Celeron 1047 UE 1.4 Ghz; i3, i7
Chipset		Intel Panther Point (PCH) QM77	Intel Panther Point (PCH) HM76	Intel Panther Point (PCH) HM76
Memory	Type / Capacity	DDR3 1333 MT/s, Max up to 16GB	DDR3 1333/1600 MT/s, Max up to 16GB	DDR3 1333/1600 MT/s, Max up to 16GB
	SO-DIMM	2	2	2
	On board memory	N/A	N/A	N/A
SSD storage	CF (CFast)	CFast	CFast (Optional)	CFast (Optional)
	mSATA	Yes	Yes	Yes
	On Board SSD	Optional	Optional	Optional
HDD Space		2.5" HDD x 1	2.5" HDD x 1	2.5" HDD x 1
VGA		Yes	Yes	Yes
DVI / HDMI		DVI / HDMI	DVI / HDMI	DVI / HDMI
USB		Built-in 4 x USB,expand up to 9 x USB (USB 3.0 x 4 + USB 2.0 x 5)	Built-in 4 x USB (USB 3.0 x 2 + USB 2.0 x 2)	Built-in 4 x USB,expand up to 9 x USB (USB 3.0 x 2+ USB 2.0 x 7)
PS2 KB/MS		Optional	N/A	Optional
COM		Built-in 4 x COM, expand up to 6 x COM	4	Built-in 4 x COM, expand up to 6 x COM
PCI / PCIe		2 (Optional)	N/A	2 (Optional)
Mini-PCIe		2	2	2
SIM Card Holder		2	2	2
GPIO		8DI / 8DO (Optional)	8DI / 8DO (Optional)	8DI / 8DO (Optional)
Ethernet		Intel GbE x 2	Intel GbE x 2	Intel GbE x 2
Mic-in / Line-out		Yes	Yes	Yes
Power Input		DC IN +12V	DC IN +12V, +9V~36V Optional	DC IN +12V ; +9V~+36V (optional)
Expansion		PoE LANs, GPS, IEEE1394, 3G, Bluetooth, WI-FI, I/O	3G,GPS, Bluetooth, WI-FI	PoE LANs, GPS, IEEE1394, 3G, Bluetooth, WI-FI, I/O
Operating Temp.		0~45°C for HDD, -20°C~60°C for mSATA / 2.5" SSD HDD	0~45°C for HDD, -20°C~60°C for mSATA / 2.5" SSD HDD	0~45°C for HDD, -20°C~60°C for mSATA / 2.5" SSD HDD
Operating Humidity		5%~95% @ 60°C, noncondensing	5%~95% @ 60°C, noncondensing	5%~95% @ 60°C, noncondensing